

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Huai-Yuan Tseng	07/27/2006
Chen-Pang Kung	07/27/2006
Horng-Chih Lin	07/30/2006
Ming-Hsien Lee	08/01/2006
RECEIVING PARTY DATA	
Name:	Industrial Technology Research Institute
Street Address:	No. 195, Section 4, Chung Hsing Road, Chutung
City:	Hsinchu
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11470627
CORRESPONDENCE DATA	
Fax Number:	(949)660-0809
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Email:	usa@jcipgroup.com.tw
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE
Address Line 1:	7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,
Address Line 4:	TAIPEI, TAIWAN 100
ATTORNEY DOCKET NUMBER:	19658-US-PA
NAME OF SUBMITTER:	Belinda Lee
Total Attachments: 3 source=19658-us-assignment#page1.tif source=19658-us-assignment#page2.tif source=19658-us-assignment#page3.tif	

CH \$40.00 11470627

PATENT

500154205

REEL: 018283 FRAME: 0312

ASSIGNMENT

WHEREAS

- | | |
|--------------------|-------------------|
| 1. Huai-Yuan Tseng | 2. Chen-Pang Kung |
| 3. Horng-Chih Lin | 4. Ming-Hsien Lee |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **STRUCTURE OF SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Section 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Tseng Hui-Yuan

Sole or First Joint Inventor: Hui-Yuan Tseng

Date: 2006.7.27

Signature: Kung Chen-Pang

Second Joint Inventor (if any): Chen-Pang Kung

Date: 2006.7.27

Signature: _____

Third Joint Inventor (if any): Horng-Chih Lin

Date: _____

Signature: _____

Fourth Joint Inventor (if any): Ming-Hsien Lee

Date: _____

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: _____

Date: _____

Sole or First Joint Inventor: Huai-Yuan Tseng

Signature: _____

Date: _____

Second Joint Inventor (if any): Chen-Pang Kung

Signature: A. C. Lin

Date: July 30, 2006

Third Joint Inventor (if any): Horng-Chih Lin

Signature: Ming-Hsien Lee

Date: Aug. 1, 2006

Fourth Joint Inventor (if any): Ming-Hsien Lee